

**Amendments to the Specification**

Please amend paragraph [0037] as follows:

[0037] Continuing on to FIG. 6, a particular solder joint between the PCB and semiconductor die with a sufficiently rigid support coating of FIG. 5C is similarly illustrated in side cross-sectional view. Compared to the conventional solder joint 30 of FIG. 3, the solder joint 130 of FIG. 6 is superior in several ways. One significant improvement can be found in the wetting angle 131 between the solder joint 130 and the die 100. If the height of the support coating is at about fifty percent of the original solder bump height, the final wetting angle 131 is typically between 50 and 60 degrees, which is markedly better than the normally resulting angle of about 25 to 35 degrees. In some instances, the final wetting angle 131 is almost equal to the pre-collapse angle between the original solder bump 112 and die 100. In some instances, the final wetting angle 131 is at least approximately 40 degrees. In any event, this significant increase in the final wetting angle substantially increases the structural strength of the formed solder joints, which improves solder joint reliability and lifespan under temperature cycling. In fact, preliminary experimental results indicate that reliability and lifespan are at least doubled for solder joints in dice having a sufficiently rigid support coating.